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HUANG et al.(10) **Pub. No.: US 2022/0393644 A1**(43) **Pub. Date: Dec. 8, 2022**(54) **INTEGRATED CIRCUIT INCLUDING
RESONANT CIRCUIT****Publication Classification**(51) **Int. Cl.**
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Shanghai (CN)(21) Appl. No.: **17/883,164**(22) Filed: **Aug. 8, 2022****Related U.S. Application Data**(63) Continuation of application No. 17/336,967, filed on
Jun. 2, 2021, now Pat. No. 11,444,572, which is a
continuation of application No. PCT/CN2018/
123980, filed on Dec. 26, 2018.(57) **ABSTRACT**

The present disclosure relates to integrated circuits. One example integrated circuit includes a first resonant circuit, a second resonant circuit, and at least one connection circuit. The first resonant circuit includes a first inductor, and the second resonant circuit includes a second inductor. The first inductor includes a first port, and the second inductor includes a second port. The at least one connection circuit is connected between the first port and the second port. The at least one connection circuit provides an electrical connection between the first port and the second port.

